1 Schematic

This application note describes how to operate the LM27961 Evaluation Module.

![Schematic Diagram]

2 Bill of Materials

Table 1. Bill of Materials

<table>
<thead>
<tr>
<th>Component Symbol</th>
<th>Value</th>
<th>Package [U.S. (Metric)]</th>
<th>Dimensions (mm)</th>
<th>Temperature Characteristic</th>
<th>Manufacturer</th>
<th>Part #</th>
</tr>
</thead>
<tbody>
<tr>
<td>LM27961</td>
<td>--</td>
<td>YZR-18 DSBGA</td>
<td>2.1 x 2.4 x 0.6</td>
<td>--</td>
<td>TI</td>
<td>LM27961</td>
</tr>
<tr>
<td>Cin, Cout, C1, C2</td>
<td>1 µF, 10V</td>
<td>0603 (1608)</td>
<td>1.6 x 0.8 x 0.8</td>
<td>X5R</td>
<td>TDK</td>
<td>C1608X5R1A105K</td>
</tr>
<tr>
<td>Dxx</td>
<td>White LEDs</td>
<td>--</td>
<td>1.5 x 2.3 x 1.4</td>
<td>--</td>
<td>OSRAM</td>
<td>LWM67C-T1U1-3C5D</td>
</tr>
<tr>
<td>Rset</td>
<td>8.3kΩ</td>
<td>0603 (1608)</td>
<td>1.6 x 0.8 x 0.8</td>
<td>--</td>
<td>Vishay-Dale</td>
<td>CRCW06048251F</td>
</tr>
<tr>
<td>Rset'</td>
<td>none</td>
<td>--</td>
<td>--</td>
<td>--</td>
<td></td>
<td>--</td>
</tr>
</tbody>
</table>

Capacitors: TDK C1608X5R1A105K, or equivalent

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3 LM27961 Evaluation Board Layout

4 Board Operation

4.1 Basic Connections

To operate the LM27961 evaluation board, connect a supply voltage (2.7V-5.5V) between board connectors VIN and GND.

Default Jumper Connections:

- **ENA:** Connects the “+” post to the middle post of the ENA header strip. This connects VIN to the ENA pin of the LM27961, enabling the part and the D1A-D4A outputs.
- **ENB:** Connects the “-” post to the middle post of the ENB header strip. This connects GND to the ENB pin of the LM27961, disabling D1B-D3B outputs.
Board Operation

- **ENB**: Connects the “-” post to the middle post of the ENB header strip. This connects GND to the ENB pin of the LM2796, disabling D1B-D3B outputs.
- **LEDx_ON**: Jumper connects the two posts of the LEDx_ON header strips. LEDA_ON connects the anodes of all 4 DxA LEDs to POUT, establishing the LED current path. LEDB_ON connects the cathodes of all 3 DxB LEDs to GND, establishing the LED current path.

When these connections are all made correctly, the main bank of LEDs will be ON (D1A-D4A). The secondary bank of 3 LEDs will be OFF.

### 4.2 $R_{SET}$ Setting LET Currents

The resistance of the $R_{SET}$ resistor sets the DC output currents of the LM27961 according to the following equation:

$$I_{Dxx} = 100 \times \frac{1.25V}{R_{SET}} \text{(typical)} \quad (1)$$

The default $R_{SET}$ on the evaluation board is 8.3kΩ, resulting in a typical DC output current of 15mA.

Component $R_{SET}$ is an optional leaded (axial) resistor replacement for the surface mount $R_{SET}$.

### 4.3 EN, ENA, AND ENB Headers: LED Activation and PWM Brightness Adjustment

The header strips ENA and ENB can be used to enable/disable the LM27961 and/or the output currents. The connections to the ENx pins provided by these posts can also be used to connect pulse-width modulated (PWM) signals to the LM27961 in order to adjust the average brightness of the LEDs.

On each of these header strips, the post labeled “+” is connected to $V_{IN}$. The post labeled “-” is connected to GND. The middle post connects to ENA and ENB, respectively.

Jumpers can be used to connect each ENx pin to either $V_{IN}$ or GND. Connecting ENA or ENB to $V_{IN}$ enables the charge pump and other internal circuitry of the LM27961. Connecting both ENA and ENB to GND places the part in Shutdown mode.

Connecting ENA to $V_{IN}$ enables the D1A-D4A LEDs. Connecting ENA to GND disables these LEDs. Similarly, connecting ENB to $V_{IN}$ enables the D1B-D3B LEDs, and connecting ENB to GND disables the DxB LEDs.

Connecting a pulse signal to the ENA and/or ENB pins can be used to adjust the brightness of each bank of LEDs. The duty cycle of the pulse signal determines the net brightness, as perceived by the human eye. For example, with a duty cycle of 50%, the LEDs will only be ON for 50% of the time, and the perceived brightness will be approximately half of what the brightness is when the output current flows continuously through the LEDs. Recommended frequency range for PWM signals: 100Hz to 1kHz.

### 4.4 Using the LEDS on Headers to Measure Output Currents

By removing the LEDx_ON jumpers, LM27961 output currents can easily be measured. Removing the jumpers disconnects the anodes (DxA) and cathodes (DxB) of all LEDs from POUT (DxA) or GND (DxB), breaking the LED current paths. By placing a current meter between the two header pins the sum total of all LED currents can be measured.

With the LEDx_ON jumpers removed, the current of an individual output can be measured by placing a current meter between a DxA header and POUT or DxB and GND.

With such a connection, the voltage on pin Dxx will be almost 0V because the series resistance of the current meter is likely to be quite small. Since the regulated output currents of the LM27961 are almost completely independent of Dxx pin voltage (provided $V_{Dxx}$ is not too high for regulation to be achieved), this measurement will still be quite accurate. For an even more precise measurement, however, a resistor or LED can be placed in series with the current meter so that the voltage at pin Dxx more closely resembles the expected forward voltage of the LED in the normal application configuration.
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